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1. Revision History

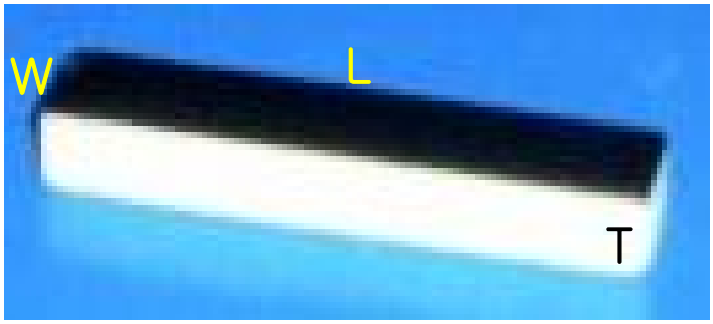
product	NKC-POS_A	Model	SRP-350IIOBE

Rev. No.	Rev. Issue	Page	Designed	Date
1.0	Appro. Issue	-	KC. NAM	2013.01.02

2. Features & Applications

2.1 Features

This ceramic chip antenna is applied to 2.4 GHz ISM band applications, i.e. Bluetooth. Zigbee, Wireless LAN, etc...

형태	Bulk Ceramic	
재질	유전체	Al_2O_3(Alumina)
	전극	은(Ag)
크기 (mm)	L = 10+/-0.1	
	W = 2+/-0.1	
	T = 1.2+/-0.1	
Weight	97~100 mg	

3. Electrical Specifications

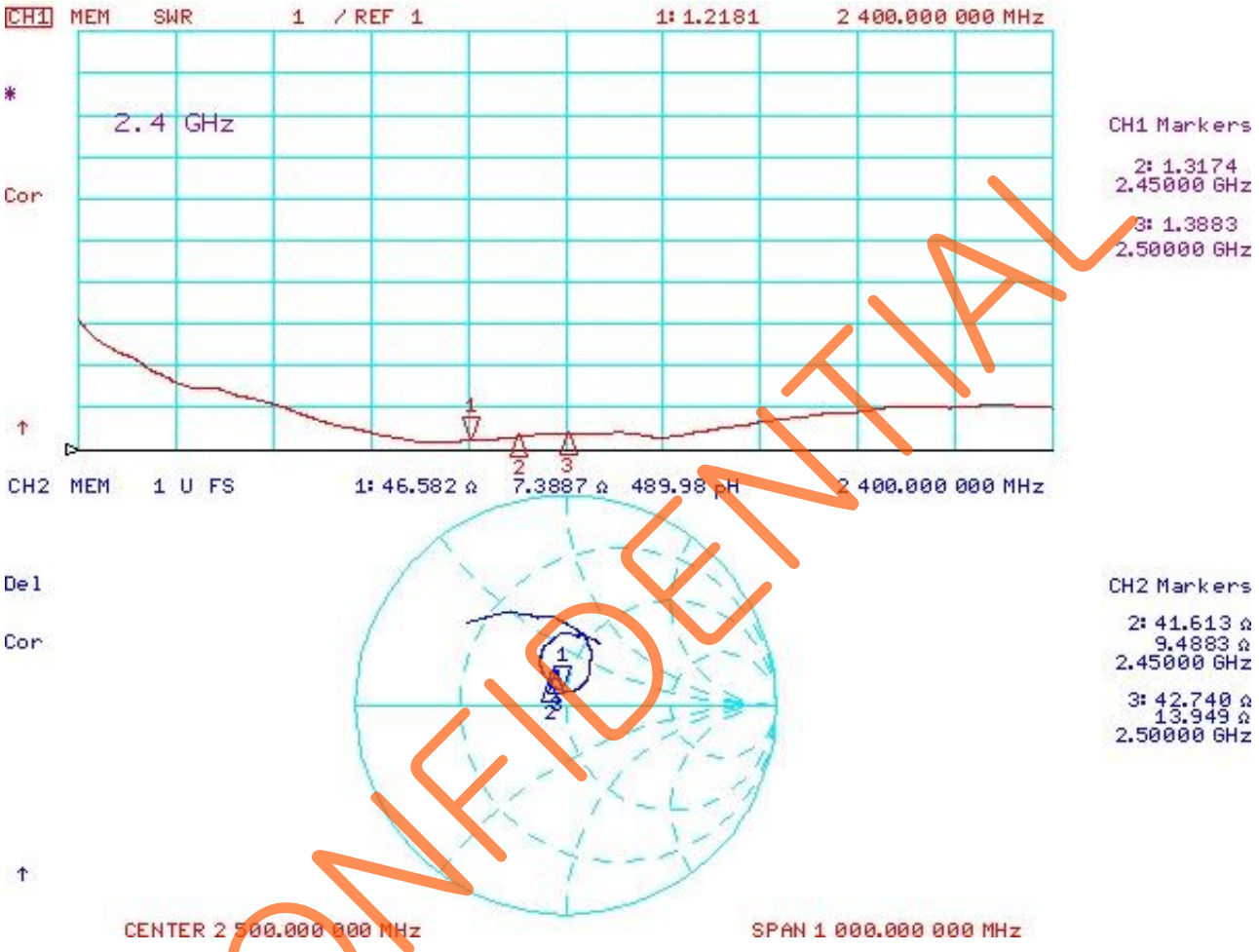
3-1.

* All item are measured in room temperature (24~25 'C).

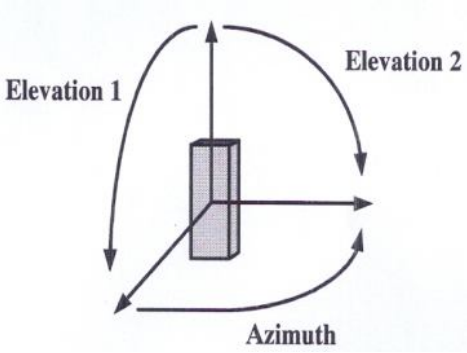
* All item are measured at customer set condition.

No.	Items	Typical Data
1	Frequency (MHz)	2400 ~2500
2	VSWR	1.5 : 1
3	Total Gain (Peak) [dBi]	0
4	Impedance	50 ohm
5	Polarization	Linear

3-2. VSWR (S11)of USER SET condition



3-3. Radiation Patterns

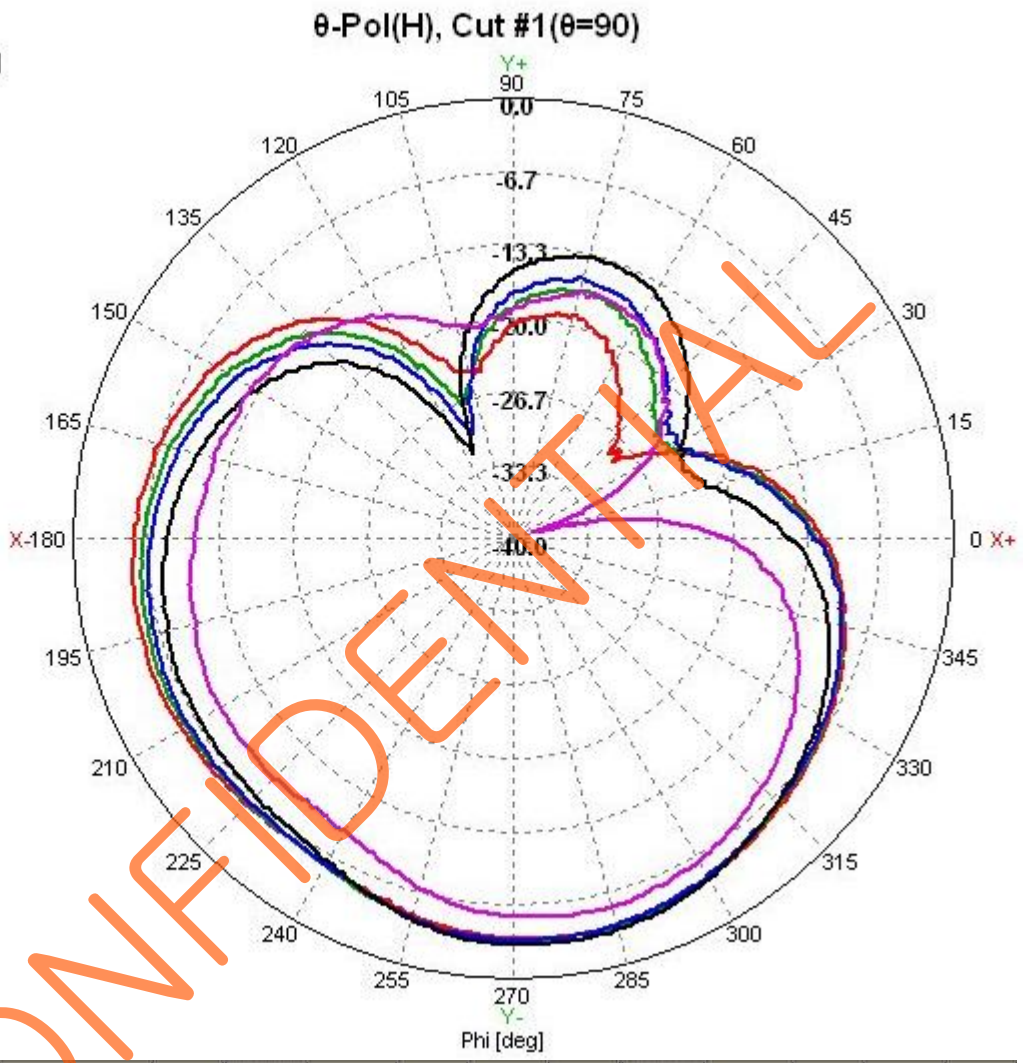


Theta	Vertical Field of measured plane
Phi	Horizontal Field of measured plane

이득[dBi] (Co-Pola)	Azimuth	Phi	Peak	-3.02
			Avg	-8.34
	Elevation	Theta	Peak	-0.94
			Avg	-5.32

(Azimuth)

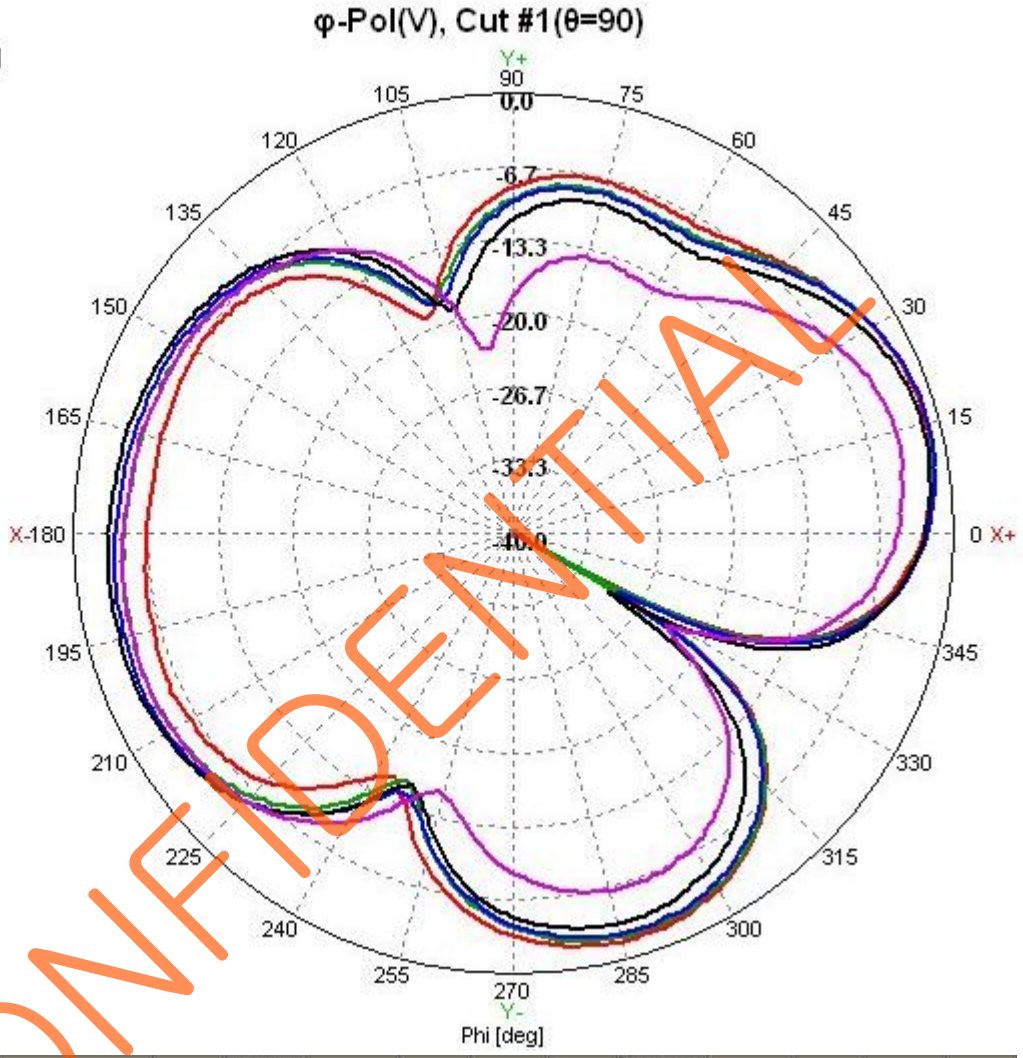
No.	Freq.
1	2.400
2	2.420
3	2.430
4	2.450
5	2.500



		θ-Pol(H)					φ-Pol(V)					PwrSum				
No	Freq.[GHz]	Avg.[dBi]	Peak[dBi]	φ[deg]	Null[dBi]	φ[deg]	Avg.[dBi]	Peak[dBi]	φ[deg]	Null[dBi]	φ[deg]	Avg.[dBi]	Peak[dBi]	φ[deg]	Null[dBi]	φ[deg]
1	2.400	-7.65	-3.47	278.00	-28.64	38.00	-5.79	-1.18	16.00	-45.14	331.00	-3.61	0.55	284.00	-17.39	112.00
2	2.420	-7.86	-3.35	277.00	-27.01	110.00	-5.46	-0.97	16.00	-36.97	331.00	-3.49	0.28	284.00	-17.16	108.00
3	2.430	-8.07	-3.40	277.00	-29.82	111.00	-5.32	-0.94	16.00	-29.11	331.00	-3.47	0.08	284.00	-17.75	109.00
4	2.450	-8.34	-3.02	278.00	-31.53	115.00	-5.61	-1.49	16.00	-30.01	328.00	-3.75	-0.23	284.00	-17.44	106.00
5	2.500	-10.65	-5.25	284.00	-38.25	17.00	-7.53	-3.98	13.00	-23.62	329.00	-5.80	-2.83	284.00	-18.68	100.00

(Elevation)

No.	Freq.
1	2.400
2	2.420
3	2.430
4	2.450
5	2.500



		θ-Pol(H)					φ-Pol(V)					PwrSum				
No	Freq.[GHz]	Avg.[dBi]	Peak[dBi]	φ[deg]	Null[dBi]	φ[deg]	Avg.[dBi]	Peak[dBi]	φ[deg]	Null[dBi]	φ[deg]	Avg.[dBi]	Peak[dBi]	φ[deg]	Null[dBi]	φ[deg]
1	2.400	-7.65	-3.47	278.00	-28.64	38.00	-5.79	-1.18	16.00	-45.14	331.00	-3.61	0.55	284.00	-17.39	112.00
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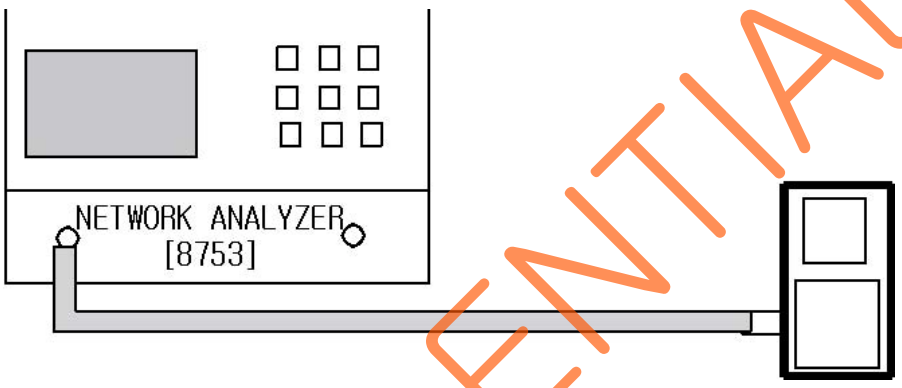
5	2.500	-10.65	-5.25	284.00	-38.25	17.00	-7.53	-3.98	13.00	-23.62	329.00	-5.80	-2.83	284.00	-18.68	100.00

4. Measurements Method & Conditions

The measurement of antenna performance is measurement of gain, radiation pattern using ORBIT/FR apparatus in Anechoic chamber and measurement of VSWR using Network analyzer.

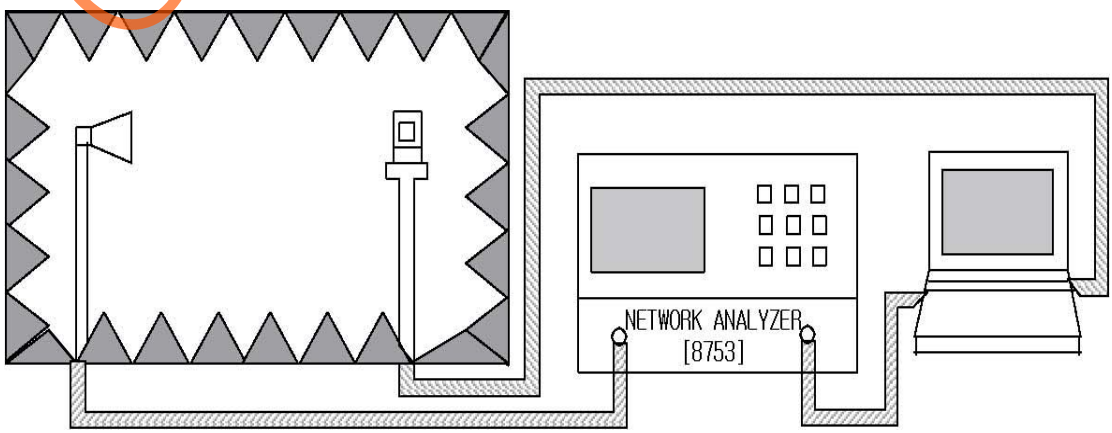
4-1. The measurement of Frequency and VSWR



[Measurement Method]

1. As seen the above, network analyzer is set up for S11 measurement.
2. The measurement frequency range is to set up from 2 GHz to 3 GHz.
3. Perform S11 one port full calibration.
4. Measure the VSWR of three points of Bluetooth frequency range such as 2.4 GHz, 2.45 GHz, and 2.5 GHz.

4-2. The measurement of Gain & Radiation Patterns

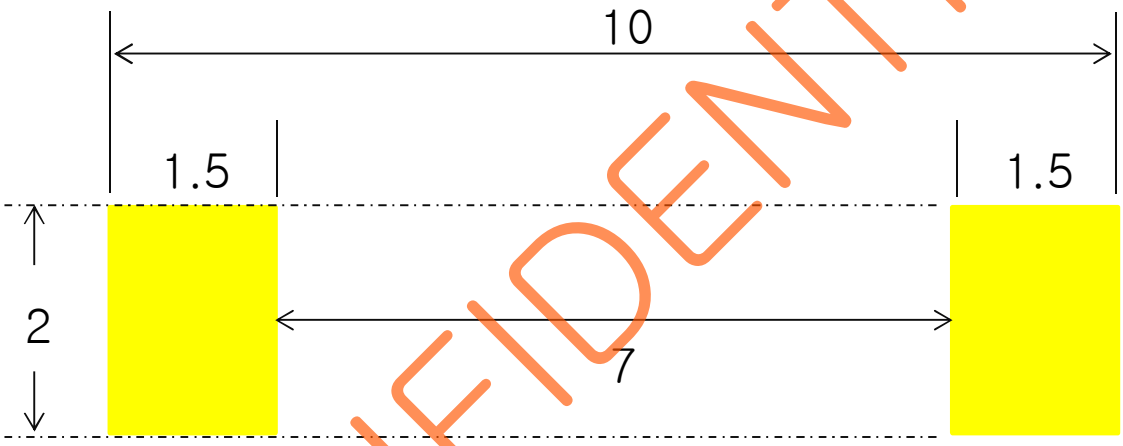


[Measurement Method]

1. As seen the above, network analyzer is to set up in Anechoic chamber.
2. As seen beneath, for the measurement planes as Azimuth, Elevation 1, and Elevation 2, measure Gain data of vertical polarization and horizontal polarization for each plane.

5. PCB Layout & Solder Pad size

5-1. Top Layout

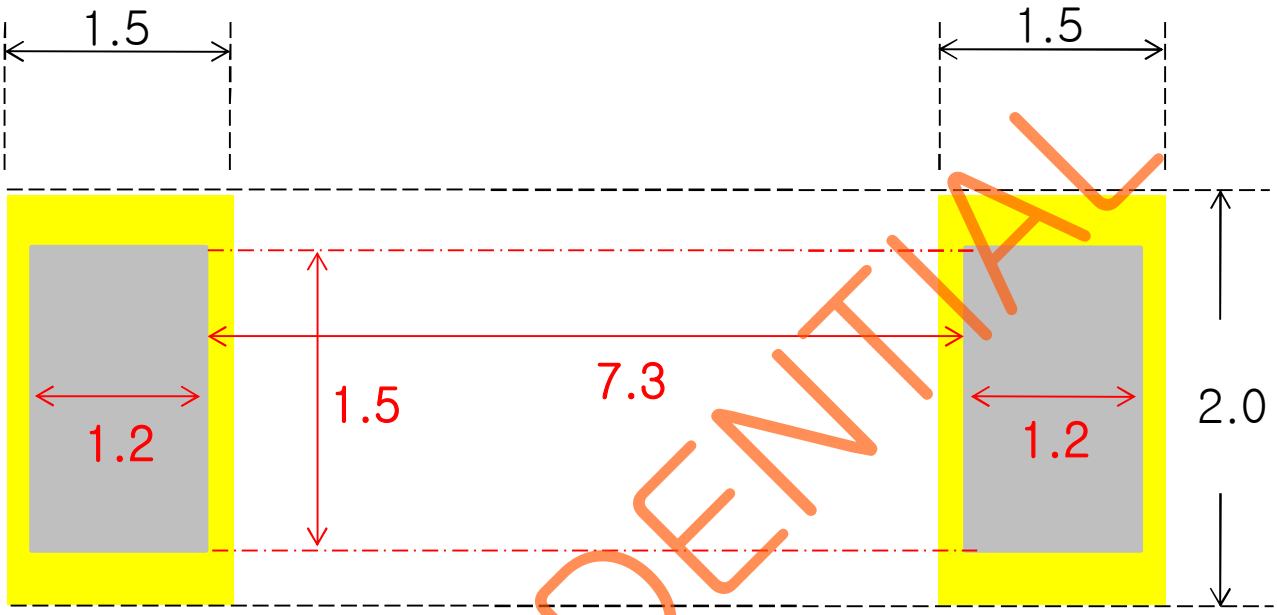


Solder Pad

Unit : mm

tolerances : +/- 0.05

5-2. Pad size & SOLDERING CREAM AREA



Unit: mm

Soldering Cream의 면적은 SMD 업체 현황(메탈 스크린 두께, 온도)에 따라 변경 될 수 있으므로 협의를 요함

Solder Pad

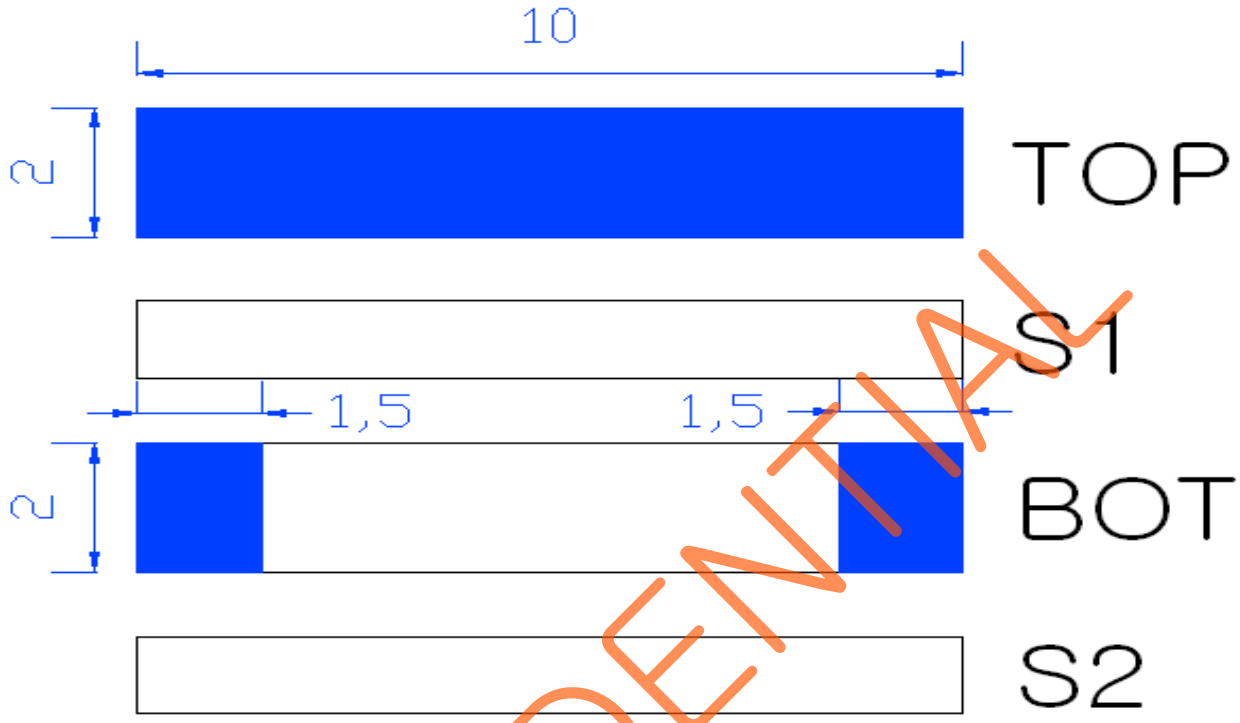
Soldering Cream

5-3. Antenna position

CHIP ANT

Solder Pad

6. Ag pattern & Dimensions



7. Marking View

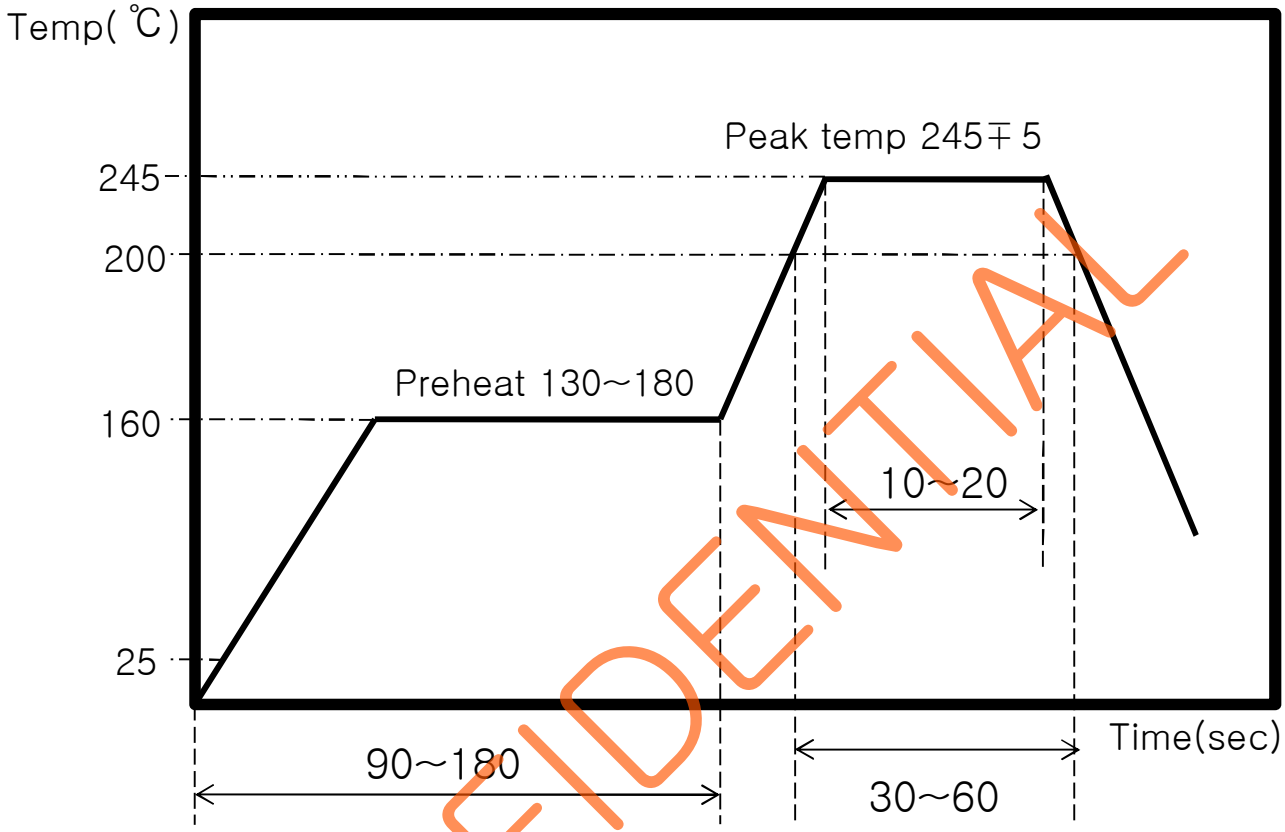
Only TOP part

7-1. 마킹 종류

* RF용 검정 잉크 사용

8. Reflow Profile

8-1. Standard reflow condition(Pb-free)

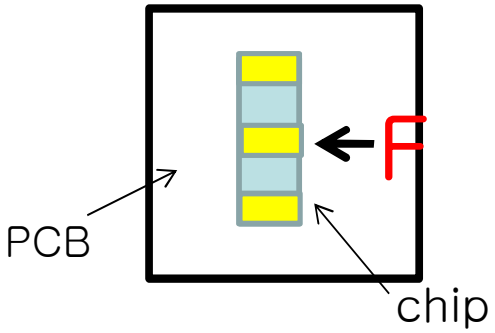


SMD 업체 현황에 따라 peak temp 및 시간은 변경 될 수 있으므로 협의를 요함

8-2. 수동 납땜 (인두기)을 할 경우(Pb-free)

인두 온도 : 340 'C / 시간 : 각 단 max 3 sec

9. Environmental Tests

No.	ITEM	TEST COND	TEST REQU
1	High Temperature Resistance	1. Temp: +125±5℃ 2. Time: 1000±24hrs 3. Measure Fc after left for 24hrs min. at room temp	1. Within electric spec(VSWR) 2. No visual damage
2	Low Temperature Resistance	1. Temp: -40±5℃ 2. Time: 1000±24hrs 3. Measure Fc after left for 48hrs min. at room temp	1. Within electric spec(VSWR) 2. No visual damage
3	Thermal Shock	1. 1cycle/step1:-40±3℃,30min step2:+125±3℃,30min 2. Number of cycle:30 3. Measure after left for 48hrs min. at room temp	1. Within electric spec(VSWR) 2. No visual damage
4	Humidity	1. Humidity:85%RH 2. Temp:+85±3℃ 3. Time:1000±24hrs 4. Measure Fc after left for 48hrs min. at room temp	1. Within electric spec(VSWR) 2. No visual damage
5	Adhesive strength of termination	1. Applied force on SMD chip till detached point from PCB.  	1. No mechanical damage by forces applied on the right 2. Strength(F)>5kgf